

Title (en)
Crimp terminal

Title (de)
Crimpklemme

Title (fr)
Borne de sertissage

Publication
EP 2876731 B1 20180502 (EN)

Application
EP 13819977 A 20130719

Priority
• JP 2012162077 A 20120720
• JP 2012192380 A 20120831
• JP 2013069692 W 20130719

Abstract (en)
[origin: EP2876731A1] In a female crimp terminal 10 having a pressure-bonding section 30 which allows pressure-bonding and connection of at least a conductor tip 201a in an insulated wire 200 obtained by coating a conductor 201 with an insulating cover 202 and having the conductor tip 201a in which the conductor 201 is exposed by peeling off the insulating cover 202 in a tip side, the pressure-bonding section 30 is constructed by arranging a conductor pressure-bonding section 30b and a cover pressure-bonding section 30a from a tip side to a base end side in a long length direction X in this order, the conductor pressure-bonding section 30b pressure-bonding the conductor tip 201a, and the cover pressure-bonding section pressure-bonding a conductor tip portion 202a in the tip side of the insulating cover 202, the cover pressure-bonding section 30a is formed into a hollow shape which can surround the conductor tip portion 202a, and the conductor pressure-bonding section 30b is formed to have a smaller diameter than the cover pressure-bonding section 30a, and is formed into a hollow shape which can surround the conductor tip 201a.

IPC 8 full level
H01R 13/52 (2006.01); **H01R 4/20** (2006.01); **H01R 4/62** (2006.01); **H01R 43/00** (2006.01); **H01R 43/02** (2006.01); **H01R 43/048** (2006.01)

CPC (source: EP US)
H01R 4/183 (2013.01 - US); **H01R 4/20** (2013.01 - EP US); **H01R 4/206** (2013.01 - US); **H01R 13/52** (2013.01 - EP US); **H01R 4/62** (2013.01 - EP US); **H01R 43/005** (2013.01 - EP US); **H01R 43/0221** (2013.01 - EP US); **H01R 43/0482** (2013.01 - EP US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 2876731 A1 20150527; **EP 2876731 A4 20160727**; **EP 2876731 B1 20180502**; CN 104094472 A 20141008; CN 104094472 B 20160525; JP 2014146609 A 20140814; JP 5535409 B1 20140702; JP 6088997 B2 20170301; JP WO2014014105 A1 20160707; KR 101529255 B1 20150616; KR 20140117607 A 20141007; US 2015126079 A1 20150507; US 9240635 B2 20160119; WO 2014014105 A1 20140123

DOCDB simple family (application)
EP 13819977 A 20130719; CN 201380007969 A 20130719; JP 2013069692 W 20130719; JP 2013544902 A 20130719; JP 2014078882 A 20140407; KR 20147023529 A 20130719; US 201414520447 A 20141022